

# International IOR Rectifier

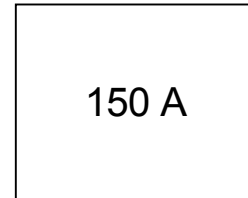
## IRKT152/04

THYRISTOR/ THYRISTOR

INT-A-pak™ Power Module

### Features

- Electrically Isolated by DBC Ceramic ( Al<sub>2</sub>O<sub>3</sub> )
- 3500 V<sub>RMS</sub> Isolating Voltage
- Industrial Standard Package
- High Surge Capability
- Glass Passivated Chips
- Simple Mounting
- UL E78996 approved 



### Applications

- Battery Charges
- Welders
- Power Converters

### Major Ratings and Characteristics

Parameters	IRKT152/04	Units
I <sub>T(AV)</sub>	150	A
@ T <sub>C</sub>	85	°C
I <sub>T(RMS)</sub>	330	A
I <sub>TSM</sub> @ 50Hz	4000	KA <sup>2</sup> s
@ 60Hz	4200	
i <sup>2</sup> t @ 50Hz	80	KA <sup>2</sup> /s
@ 60Hz	73	
i <sup>2</sup> √t	800	KA <sup>2</sup> /√s
V <sub>RRM</sub>	400	V
T <sub>STG</sub> range	-40 to 150	°C
T <sub>J</sub> range	-40 to 125	

### CASE STYLE NEW INT-A-PAK



**ELECTRICAL SPECIFICATIONS**

## Voltage Ratings

Type number	$V_{RRM}/V_{DRM}$ , Maximum repetitive peak reverse voltage V	$V_{RSM}/V_{DSM}$ , Maximum non-repetitive peak reverse voltage V	$I_{RRM}/I_{DRM}$ @ 125°C mA
IRKT152/04	400	500	50

## On-state Conduction

Parameter	IRKT152/04	Units	Conditions
$I_{T(AV)}$ Max. average on-state current @ Case temperature	150	A	180° conduction half sine wave
	85	°C	
$I_{T(RMS)}$ Maximum RMS on-state current	330	A	as AC switch
$I_{TSM}$ Maximum peak, one-cycle on-state, non-repetitive surge current	4000	A	t = 10ms No voltage
	4200		t = 8.3ms reapplied
	3350		t = 10ms 100% $V_{RRM}$
	3500		t = 8.3ms reapplied
$I^2t$ Maximum $I^2t$ for fusing	80	KA <sup>2</sup> s	t = 10ms No voltage
	73		t = 8.3ms reapplied
	56		t = 10ms 100% $V_{RRM}$
	51		t = 8.3ms reapplied
$I^2\sqrt{t}$ Maximum $I^2\sqrt{t}$ for fusing	800	KA <sup>2</sup> √s	t = 0.1 to 10ms, no voltage reapplied
$V_{T(TO)}$ Value of threshold voltage	0.82	V	@ $T_J$ max.
$r_t$ On-state slope resistance	1.44	mΩ	
$V_{TM}$ Maximum on-state voltage drop	1.44	V	$I_{pk} = 470A, T_J = 25°C$
$I_H$ Maximum Holding Current	200	mA	$T_J = 25°C$ , anode supply = 6V, resistive load, gate open circuit
$I_L$ Maximum Latching Current	400		$T_J = 25°C$ , anode supply = 6V, resistive load

## Switching

Parameter	Value	Units	Conditions
$t_{gd}$ Typical delay time	1	μs	$T_J = 25°C$ Gate Current=1A $di/dt=1A/\mu s$
$t_{gr}$ Typical rise time	2		$T_J = 25°C$ $V_d=0,67\% V_{DRM}$
$t_q$ Typical turn-off time	50 - 200		$I_{TM} = 300 A; -di/dt = 15 A/\mu s; T_J = T_J \text{ max}$ $V_f = 50 V; dV/dt = 20 V/\mu s; \text{Gate } 0 V, 100\Omega$

## Blocking

Parameter	Value	Units	Conditions
$I_{RRM}$ Maximum peak reverse and off-state leakage current	50	mA	$T_J = 125°C$
$I_{DRM}$			
$V_{INS}$ RMS isolation voltage	3500	V	50Hz, circuit to base, all terminals shorted, t = 1s
dV/dt critical rate of rise of off-state voltage	1000	V/μs	$T_J = T_J \text{ max.}, \text{exponential to } 67\% \text{ rated } V_{DRM}$

**Triggering**

Parameter	IRKT152/04	Units	Conditions	
$P_{GM}$ Max. peak gate power	12	W	$t_p \leq 5ms, T_J = T_{Jmax}$ .	
$P_{G(AV)}$ Max. average gate power	3	W	$f=50Hz, T_J = T_{Jmax}$ .	
$I_{GM}$ Max. peak gate current	3	A	$t_p \leq 5ms, T_J = T_{Jmax}$ .	
$-V_{GT}$ Max. peak negative gate voltage	10	V		
$V_{GT}$ Max. required DC gate voltage to trigger	4	V	Anodesupply=6V, resistive load; Ra= 1Ω	
	2.5			$T_J = -40^\circ C$
	1.7			$T_J = 25^\circ C$
$I_{GT}$ Max. required DC gate current to trigger	270	mA	Anodesupply=6V, resistive load; Ra= 1Ω	
	150			$T_J = -40^\circ C$
	80			$T_J = 25^\circ C$
$V_{GD}$ Max. gate voltage that will not trigger	0.3	V	@ $T_J = T_{Jmax}$ , rated $V_{DRM}$ applied	
$I_{GD}$ Max. gate current that will not trigger	10	mA		
$di/dt$ Max. rate of rise of turned-on current	300	A/μs	@ $T_J = T_{Jmax}$ , $I_{TM} = 400A$ rated $V_{DRM}$ applied	

**Thermal and Mechanical Specifications**

Parameter	IRKT152/04	Units	Conditions
$T_J$ Max. junction operating temperature range	-40 to 125	°C	
$T_{stg}$ Max. storage temperature range	-40 to 150	°C	
$R_{thJC}$ Max. thermal resistance, junction to case	0.18	K/W	DC operation, per junction
$R_{thCS}$ Max. thermal resistance, case to heatsink	0.05	K/W	Mounting surface smooth, flat and greased Per module
T Mounting IAP to heatsink torque ± 10% busbar to IAP	4 to 6	Nm	A mounting compound is recommended and the torque should be rechecked after a period of 3 hours to allow for the spread of the compound. Lubricated threads.
wt Approximate weight	200 (7.1)		
Case Style	New Int-A-Pak		

**ΔR Conduction (per Junction)**

(The following table shows the increment of thermal resistance  $R_{thJC}$  when devices operate at different conduction angles than DC)

Devices	Sinusoidal conduction @ $T_J$ max.					Rectangular conduction @ $T_J$ max.					Units
	180°	120°	90°	60°	30°	180°	120°	90°	60°	30°	
IRKT152/04	0.007	0.010	0.013	0.016	0.017	0.009	0.012	0.014	0.016	0.017	K/W

# IRKT152/04

Bulletin I27122 rev. C 04/02

## Ordering Information Table

Device Code				
IRK	T	152	/	04
①	②	③		④
1	- Module Type			
2	- Circuit Configuration			
3	- Current Rating: $I_{T(AV)}$			
4	- Voltage Code: Code x 100 = $V_{RRM}$			

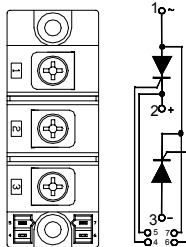
## Outline Table

The drawing shows the following dimensions:

- Top view: Total width 94 [3.70"], distance between screw centers 66 [2.60"], individual screw spacing 17 [0.67"], 23 [0.91"], 23 [0.91"], and 5 [0.20"].
- Side view: Total height 29 [1.15"], mounting hole offset 9 [0.33"], mounting hole diameter  $\phi 6.5$  [0.25" DIA], and mounting hole depth 7 [0.28"].
- Detail view: Mounting hole diameter  $\phi 6.5$  [0.25" DIA], hole depth 7 [0.28"], and screw hole diameter  $2.8 \times 0.8$  [0.11" x 0.03"].
- Other dimensions: 30 [1.18"], 14.5 [0.57"], 35 [1.38"], and 37 [1.44"].

3 Screws M6x10

All dimensions are in millimeters



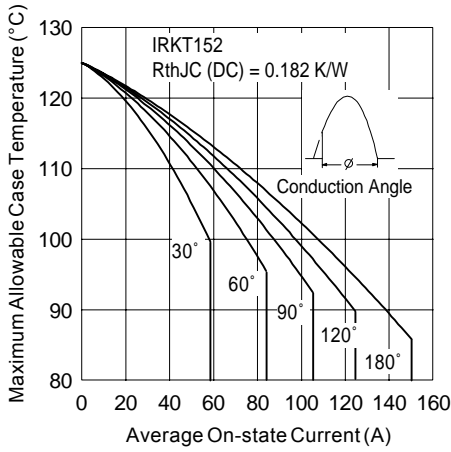


Fig. 1 - Current Ratings Characteristics

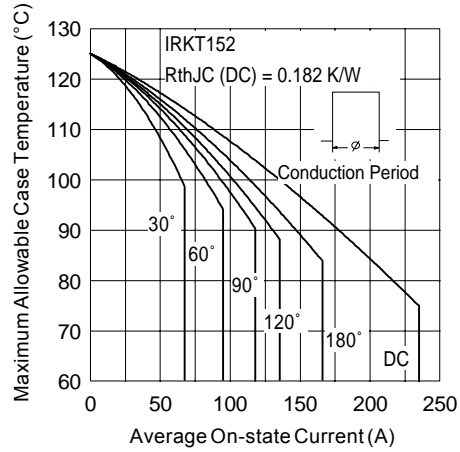


Fig. 2 - Current Ratings Characteristics

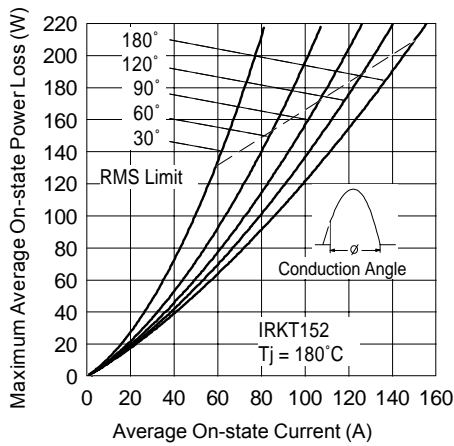


Fig. 3 - Forward Power Loss Characteristics

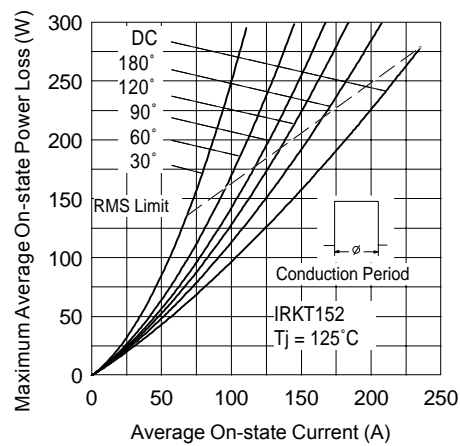


Fig. 4 - Forward Power Loss Characteristics

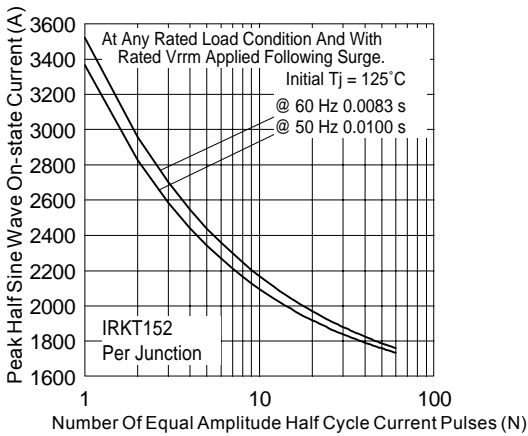


Fig. 5 - Maximum Non-Repetitive Surge Current

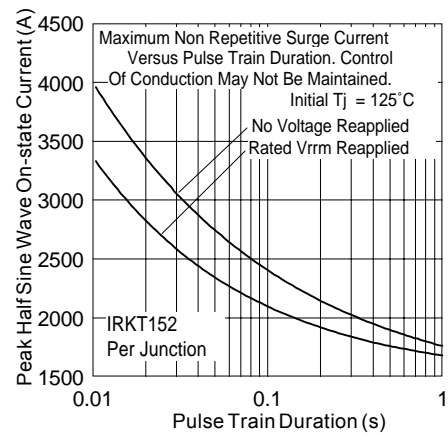


Fig. 6 - Maximum Non-Repetitive Surge Current

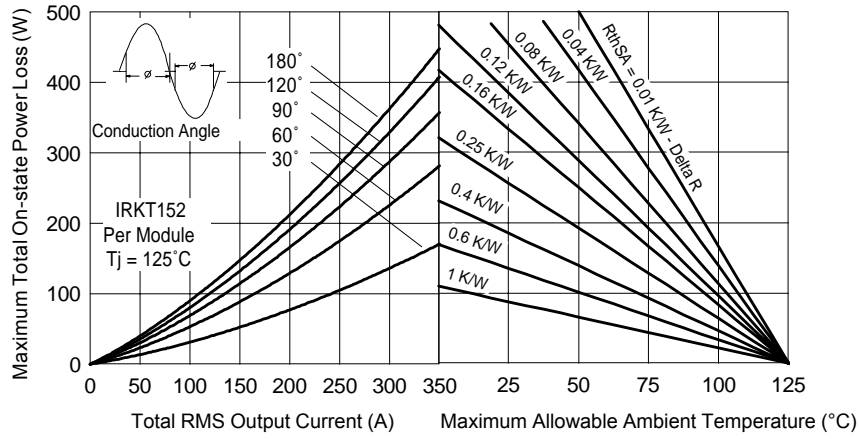


Fig.7 - On State Power Loss Characteristics

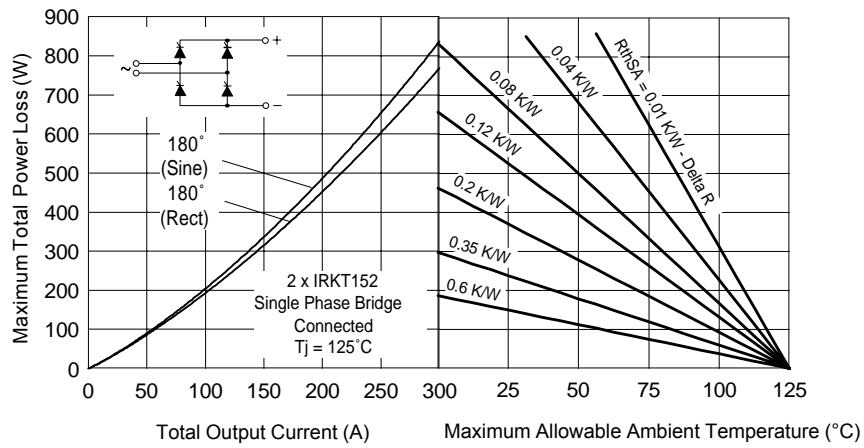


Fig.8 - On State Power Loss Characteristics

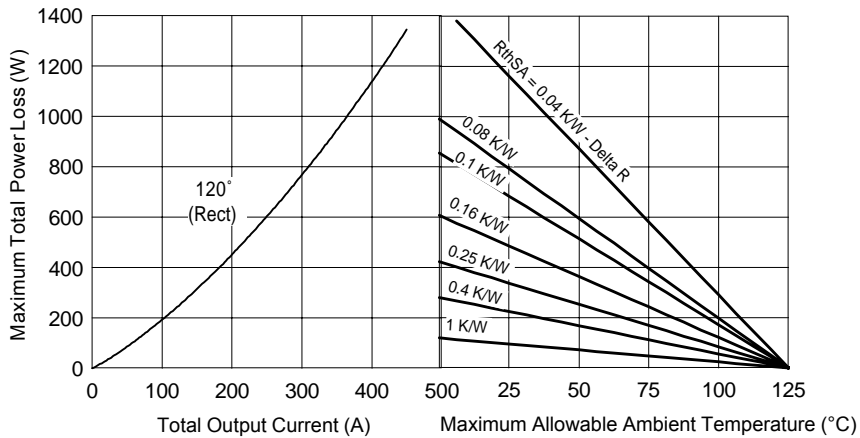


Fig.9 - On State Power Loss Characteristics

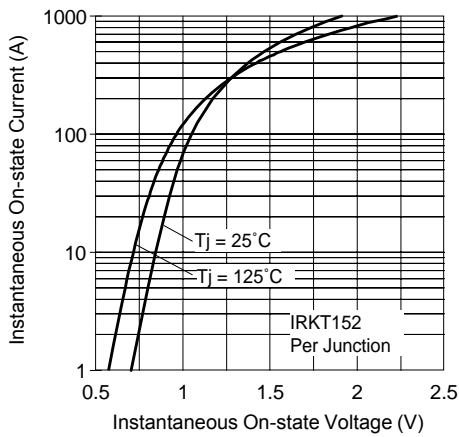


Fig. 10 - On-State Voltage Drop Characteristics

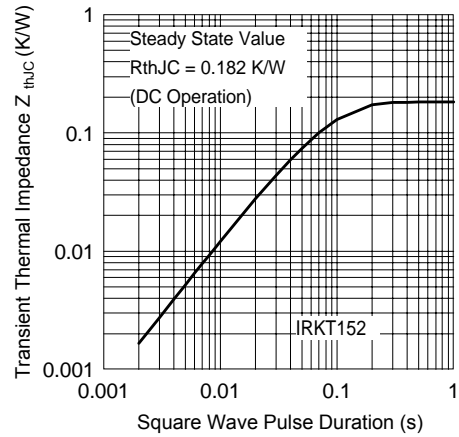


Fig. 11 - Thermal Impedance  $Z_{thJC}$  Characteristics

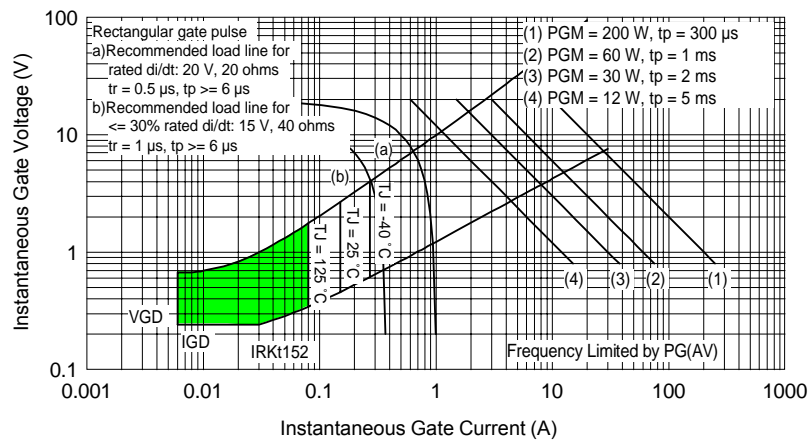


Fig. 12 - Gate Characteristics

Data and specifications subject to change without notice.  
This product has been designed and qualified for Multiple Level.  
Qualification Standards can be found on IR's Web site.